



FEATURES

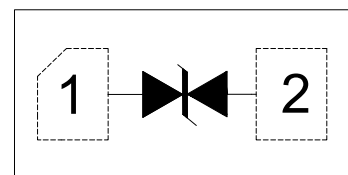
- ✧ Protects one bi-directional I/O line
- ✧ Low clamping voltage
- ✧ Low operating voltage: 3.3V
- ✧ Low leakage current
- ✧ RoHS compliant



DFN1006-2L(Bottom view)

MAIN APPLICATIONS

- ✧ Cell phone handsets and accessories
- ✧ Personal digital assistants (PDA's)
- ✧ Notebooks, desktops, and servers
- ✧ Portable instrumentation
- ✧ Digital cameras



Pin Configuration(Top view)

PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ IEC61000-4-5 (Lightning) 7A (8/20μs)

MECHANICAL CHARACTERISTICS

- ✧ DFN1006-2L package
- ✧ Molding compound flammability rating: UL 94V-0
- ✧ Quantity per reel: 10,000pcs
- ✧ Lead finish: lead free
- ✧ Marking code: 3B

ABSOLUTE MAXIMUM RATINGS (T_A=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20μs waveform	P _{PP}	80	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	+/- 30	kV
ESD per IEC 61000-4-2 (Contact)		+/- 30	
Lead soldering temperature	T _L	260 (10 sec.)	°C
Operating junction temperature range	T _J	-55 to +125	°C
Storage temperature range	T _{STG}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V_{RWM}				3.3	V
Reverse breakdown voltage	V_{BR}	$I_T=1\text{mA}$	3.6			V
Reverse holding voltage	V_H	$I_H=50\text{mA}$	3.5			V
Reverse leakage current	I_R	$V_{RWM}=3.3\text{V}$			1.0	μA
Peak pulse current	I_{PP}	$t_P=8/20\mu\text{s}$			7	A
Clamping voltage	V_C	$I_{PP}=7\text{A}, t_P=8/20\mu\text{s}$		9	12	V
Junction capacitance	C_J	$V_{RWM}=0\text{V}, f=1\text{MHz}$		15	20	pF

RATINGS AND V-I CHARACTERISTICS CURVES ($T_A=25^{\circ}\text{C}$, unless otherwise noted)

FIG.1: V- I curve characteristics (Bi-directional)

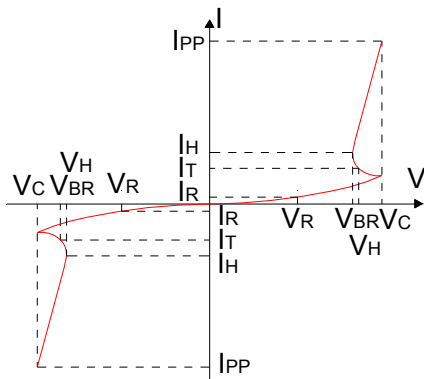


FIG.2: Pulse waveform (8/20 μs)

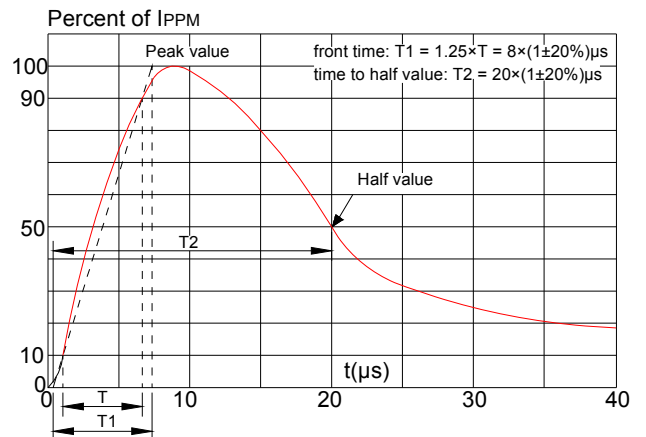


FIG.3: Pulse derating curve

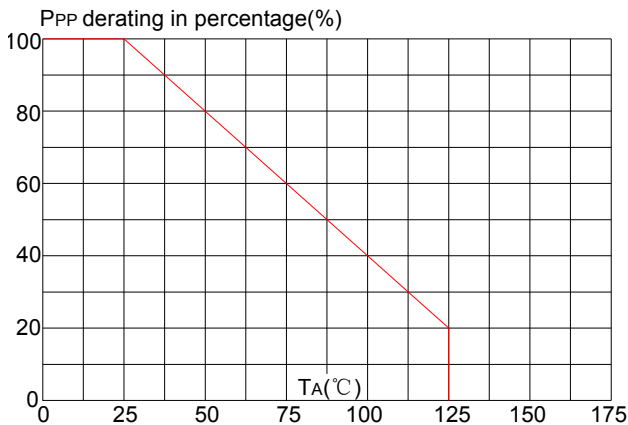
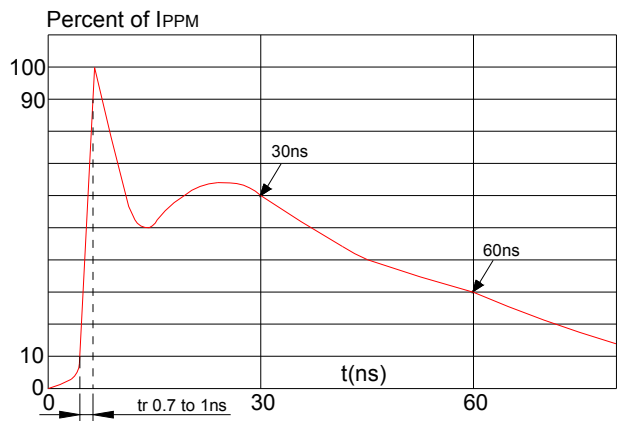
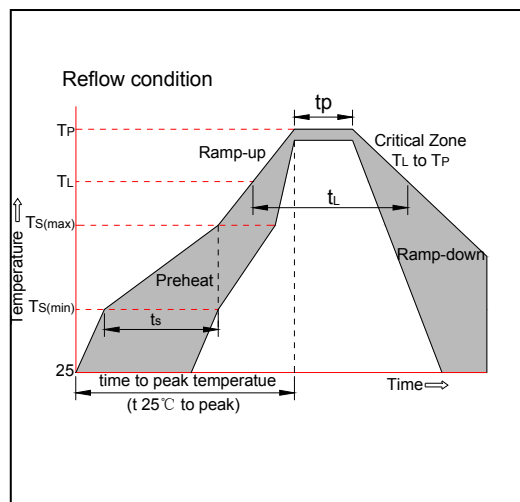


FIG.4: ESD clamping (30kV contact)

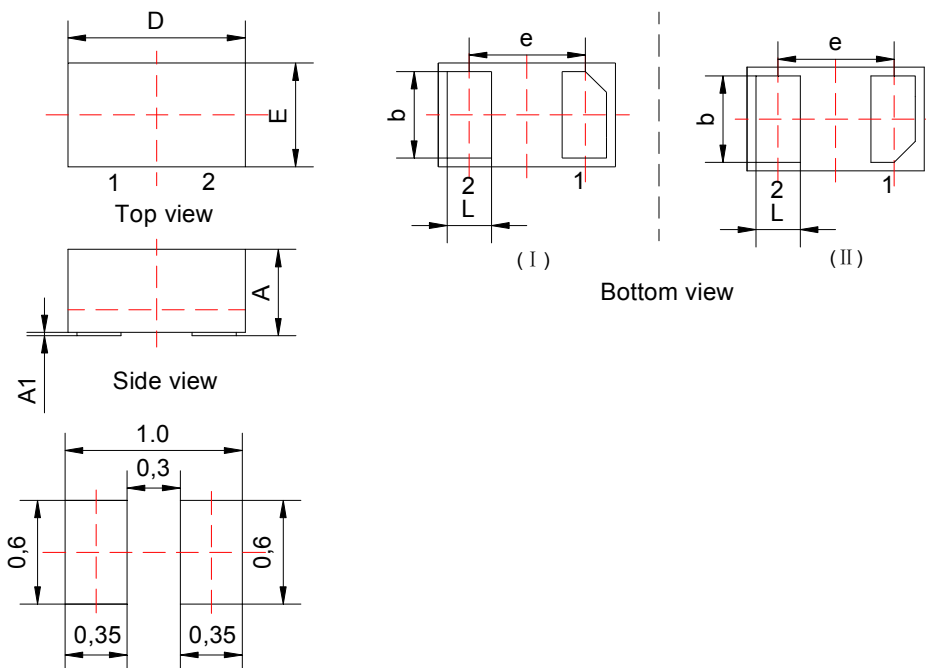


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



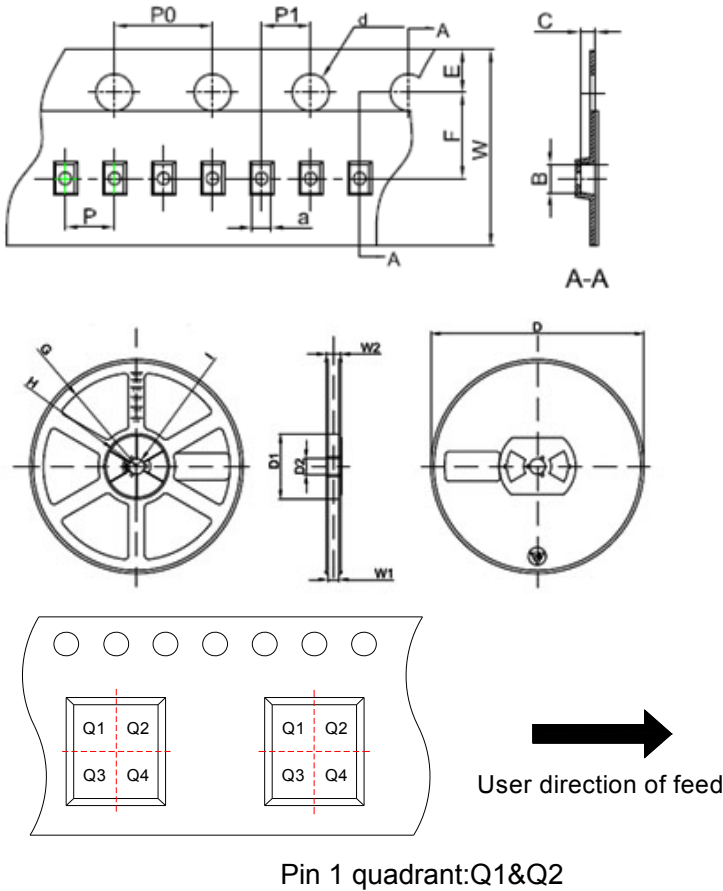
PACKAGE MECHANICAL DATA



Recommended soldering footprint(mm)

Symbol	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.40	0.50	0.55	0.016	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.45	0.50	0.55	0.018	0.020	0.022
D	0.95	1.00	1.05	0.037	0.039	0.041
e	0.65BSC			0.026BSC		
E	0.55	0.60	0.65	0.022	0.024	0.026
L	0.20	0.25	0.30	0.008	0.010	0.012

TAPE AND REEL INFORMATION-DFN1006-2L



Symbol	Millimeters	Inches
	Typ.	Typ.
a	0.66	0.026
B	1.15	0.045
C	0.66	0.026
d	Φ1.50	Φ0.059
E	1.75	0.069
F	3.50	0.138
P0	4.00	0.157
P	2.00	0.079
P1	2.00	0.079
W	8.00	0.315
D	Φ178	Φ7.008
D1	54.40	2.142
D2	13.00	0.512
G	R78.00	R3.071
H	R25.60	R1.008
I	R6.50	R0.256
W1	9.50	0.374
W2	12.30	0.484

Packaging Description:

DFN1006-2L parts are shipped in tape. The carrier tape is made from a dissipative(carbon filled) polycarbonate resin. The cover tape is a multilayer film(heat activated adhesive in nature)primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 10,000units per 7" or 17.8cm diameter reel. The reels are clear in color and made of polystyrene plastic(anti-static coated).

ORDERING INFORMATION

PART No.	PACKAGE TYPE	QUANTITY(PCS) REEL	DESCRIPTION
JEB03DF	DFN1006-2L	10,000	7 inch reel pack

MARKING CODE

Part Number	Marking Code
JEB03DF	<div style="border: 1px solid black; padding: 10px; display: inline-block;"> <p style="font-size: 24px; margin: 0;">3B</p> </div>

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